

Features

- Fully qualified end product with Bluetooth[™] v2.0, CE and FCC
- Low power consumption
- Integrated high output antenna
- Transmit power up to +8dBm
- Class1/ 2/ 3 Configurable
- Range up to 150m (line of sight)
- Piconet and Scatternet capability, support for up to 7 slaves
- Require only few external components
- Industrial temperature range -40°C to +85°C
- Serial interface up to 1.5Mbps
- Extensive digital and analog I/O interface
- 16-bit Stereo codec
- 32-bit Kalimba DSP for enhanced audio applications and other general purpose applications
- Many digital audio options: PCM, I²S and SPDIF
- Large internal memory for custom applications
- RoHS compliant

Applications

- Stereo headphones
- Automotive hands-free kits
- Echo cancellation
- High performance telephony headsets
- Industrial and domestic appliances
- Medical systems
- Automotive applications
- Stand-alone sensors
- Embedded systems
- Cordless headsets
- Handheld, laptop and desktop computers
- Mobile phones





BLUETOOTH is a trademark owned by Bluetooth SIG, Inc., U.S.A. and licensed to Free2move

General Description

F2M03MLA is a low power embedded Bluetooth[™] v2.0 multimedia module with an on board antenna, integrated stereo amplifier and a 32 bit digital signal processor (DSP) allowing enhanced audio algorithms such as MP3 decoding and advanced echo cancellation as well as other general purpose applications. The module is a fully Bluetooth[™] compliant device for audio and data communication. With a transmit power of up to +8 dBm and receiver sensibility of down to -81dBm combined with stereo sound and low power consumption the F2M03MLA is suitable for the most demanding audio applications. The module is fully Bluetooth™ v2.0 qualified and it is certified according to CE and FCC, which give fast and easy Plug-and-Go implementation and short time to market.

F2M03MLA has by default the very easy-to-use Wireless Audio Headset firmware consisting of five Bluetooth profiles: Stereo Headset, HandsFree, A2DP, AVRCP and SPP profile. The module can optionally be delivered with customized firmwares.



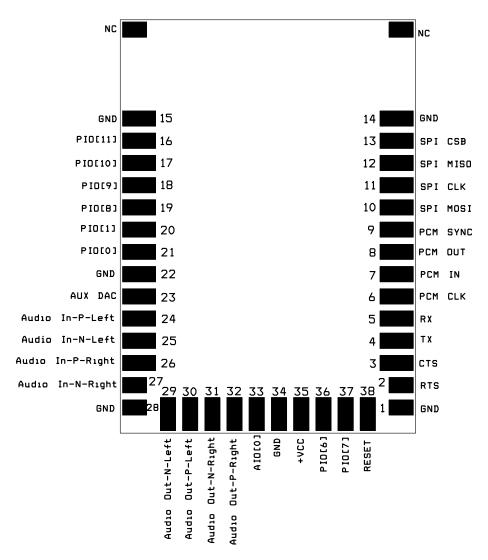


Table of contents

1	Device pinout3							
2	Device terminal functions4							
3	Electrical Characteristics							
4	Rac	lio Characteristics	.9					
5	Firr	nware versions	10					
	5.1 5.2	Wireless Audio Customised firmwares						
6	Dev	rice terminal description1	13					
	6.1 6.2 6.3 6.4 6.5 6.6 6.7	Stereo Audio Interface	16 31 33 33 34					
7	Арр	plication information	36					
	7.1 7.2 7.3	Recommended land pattern Layout guidelines Typical application schematic	37 38					
8	Pac	kage information4	10					
9	Cer	tifications	11					
	9.1 9.2 9.3	Bluetooth	41					
1() Roł	IS and WEEE Statement	13					
1'	І Тар	e and Reel information	14					
	11.1 11.2	Package Tape dimensions	44					
12	2 Ord	lering information	15					
13	B Doc	cument history	16					
14	4 Acronyms and definitions47							



1 Device pinout



Pinout of the F2M03MLA seen from the component side [TOP VIEW]



2 Device terminal functions

Ground	Pin	Pin type	Description
GND	1,14,15,22, 28,34	VSS	Ground connections
Power supplies	Pin	Pin type	Description
+VCC	35	VDD	Positive voltage supply (3.0-3.6)
Analog I/O	Pin	Pin type	Description
AIO[0]	33	Bi-directional	Programmable input/output line also possible to use as digital I/O
AUX DAC	23	Analogue output	Voltage DAC output
Reset	Pin	Pin type	Description
RESET	38	CMOS input with internal pull-up (10k Ω)	Reset if low. Input debounced so must be low for >5ms to cause a reset
Test and debug	Pin	Pin type	Description
SPI MISO	12	CMOS output, tristatable with weak internal pull-down	Serial Peripheral Interface data output
SPI CSB	13	CMOS input with weak internal pull-up	Chip select for Synchronous Serial Interface, active low
SPI CLK	11	CMOS input with weak internal pull-down	Serial Peripheral Interface clock
SPI MOSI	10	CMOS input with weak internal pull-down	Serial Peripheral Interface data input
UART	Pin	Pin type	Description
CTS	3	CMOS input with weak internal pull-down	UART clear to send active low
TX	4	CMOS output	UART data output active high
RTS	2	CMOS output, tristatable with internal pull-up	UART request to send active low
RX	5	CMOS input with weak internal pull-down	UART data input active high
	Pin	Pin type	Description
PCM_OUT / SPDIF_OUT / SD_OUT	8	CMOS output, tristatable with internal weak pull down	Synchronous data output
PCM_SYNC / WS	9	Bi-directional with weak internal pull-down	Synchronous data SYNC
PCM_IN / SPDIF_IN / SD_IN	7	CMOS input, with weak internal pull-down	Synchronous data input
PCM_CLK / SCK	6	Bi-directional with weak internal pull-down	Synchronous data clock
AUDIO	Pin	Pin type	Description
In-P-Left	24	Analogue input	Microphone input positive (left side)
In-N-Left	25	Analogue input	Microphone input negative (left side)
In-P-Right	26	Analogue input	Microphone input positive (right side)
In-N-Right Out-N-Left	27 29	Analogue input Analogue output	Microphone input negative (right side) Speaker output negative (left side)
Out-P-Left	30	Analogue output	Speaker output negative (left side)
Out-N-Right	31	Analogue output	Speaker output positive (left side)
Out-P-Right	32	Analogue output	Speaker output positive (right side)
PIO	Pin	Pin type	Description
PIO[11]	16	Bi-directional with programmable strength internal pull-up/down	Programmable input/output line
PIO[10]	17	Bi-directional with programmable strength internal pull-up/down	Programmable input/output line
PIO[9]	18		Programmable input/output line
PIO[8]	19		Programmable input/output line
PIO[7]	37	Bi-directional with programmable strength internal pull-up/down	Programmable input/output line
PIO[6]	36	Bi-directional with programmable strength internal pull-up/down	Programmable input/output line
PIO[1]	20	Bi-directional with programmable strength internal pull-up/down	Programmable input/output line
PIO[0]	21	Bi-directional with programmable strength internal pull-up/down	Programmable input/output line or Optionally WLAN_Active/Ch_Data input for co-existence signalling
Not connected	Pin	Pin type	Description
			Soldering pads for stability



3 Electrical Characteristics

Absolute Maximum Ratings

Rating	Min	Max
Storage Temperature	-40°C	+85°C
Breakdown supply voltage	-0.4V	5.60V

Recommended Operating Conditions*

Rating	Min	Max
Operating temperature range	-40°C	+85°C
Supply voltage	3.1V	3.6V

*F2M03MLA meet the Bluetooth v2.0 specification when used in the recommended operating condition.

Digital Terminals

Digital Terminals	Min	Тур	Max	Unit
Input Voltage				
V_{IL} input logic level low, 2.7V \leq VDD \leq 3.0V	-0.4	-	+0.8	V
V _{IH} input logic level high	0.7VDD	-	VDD+0.4	V
Output Voltage				
V_{OL} output logic level low, (I _O = 4.0mA), 2.7V \leq VDD \leq 3.0V	-	-	0.2	V
V_{OH} output logic level high, (I_{\text{O}} = 4.0mA), 2.7V \leq VDD \leq 3.0V	VDD-0.2	-	-	V
Input and tristate current				
Strong pull-up	-100	-40	-10	μA
Strong pull-down	+10	+40	+100	μA
Weak pull-up	-5.0	-1.0	-0.2	μA
Weak pull-down	+0.2	+1.0	+5.0	μA
I/O pad leakage current	-1	0	+1	μA
C ₁ Input Capacitance	1.0	-	5.0	pF

Auxiliary ADC

Auxiliary ADC	, 8-bit resolution	Min	Тур	Max	Unit
Resolution		-	-	8	Bits
Input voltage range (LSB size = 1.8/255= 7.1mV)	0	-	1.8	V	
Accuracy	INL	-1	-	1	LSB
(Guaranteed monotonic)	DNL	0	-	1	LSB
Offset		-1	-	1	LSB
Gain Error		-0.8	-	0.8	%
Input Bandwidth		-	100	-	KHz
Conversion time	-	2.5	-	μS	
Sample rate*		-	-	700	Sample/s

*The ADC is accessed through the VM function. The sample rate given is achieved as a part of this function



Auxiliary DAC

Auxiliary DAC, 8-bit resolution	Min	Тур	Max	Unit
Resolution	-	-	8	Bits
Average output step size	12.1	12.9	14.1	mV
Output Voltage		Monotonic		
Voltage range (I ₀ =0mA)	0	-	VDD	V
Current range	-10.0	-	+0.1	mA
Minimum output voltage (Io=100µA)	0	-	0.2	V
Maximum output voltage (I ₀ =10mA)	VDD-0.3	-	VDD	V
High impedance leakage current	-1	-	+1	μA
Offset	-220	-	+120	MV
Integral non-linearity	-2	-	+2	LSB
Settling time (50pF load)	-	-	10	μS

Notes:

Current drawn into a pin is defined as positive; current supplied out of a pin is defined as negative.

Stereo Audio CODEC Characteristics

ADC

Parameter	Symbol	Conditions		Min	Тур	Max	Unit
Resolution	NOB			-	-	16	Bits
Input sample rate	F _{sample}			8	-	44.1	kHz
Signal to noise ratio +	SINAD	$0 \rightarrow \frac{1}{2}F_{sample}$	F _{sample} =8kHz	-	84	-	dB
distortion ¹		f _{in} =1kHz	F _{sample} =11.025kHz	-	83	-	dB
			F _{sample} =16kHz	-	84	-	dB
			F _{sample} =22.050kHz	-	83	-	dB
			F _{sample} =32kHz	-	80	-	dB
			F _{sample} =44.1kHz	-	74	-	dB
Digital gain				-24	-	21.5	dB

DAC

Parameter	Symbol	Co	Conditions		Тур	Max	Unit
Resolution	NOB			-	-	16	Bits
Output sample rate	F _{sample}			8	-	48	kHz
Gain resolution				-	3	-	dB
Signal to noise ratio +	SINAD	0 → 20kHz,	F _{sample} =8kHz	-	79	-	dB
distortion ¹		f _{in} =1kHz	F _{sample} =11.025kHz	-	78	-	dB
			F _{sample} =16kHz	-	79	-	dB
			F _{sample} =22.050kHz	-	88	-	dB
			F _{sample} =32kHz	-	90	-	dB
			F _{sample} =44.1kHz	-	90	-	dB
			F _{sample} =48kHz	-	89	-	dB
Digital gain				-24	-	21.5	dB

¹Measurements refer to digital part only

Audio Input, Microphone Amplifier

	Min	Тур	Max	Unit
Input full scale at maximum gain	-	4	-	mV rms
Input full scale at minimum gain	-	400	-	mV rms
Gain resolution	-	3	-	dB
Distortion at 1kHz	-	-	-74	dB
Input referenced rms noise	-	8	-	μV rms
3dB Bandwidth	-	17	-	kHz
Input impedance	-	20	-	kΩ
THD+N (microphone input) @ 30mV rms input	-	-66	-	dB
THD+N (line input) @ 300mV Ω input ²	-	-74	-	dB



Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Allowed Load		Resistive	16	-	0.C	Ω
Allowed Load		Capacitive	-	-	500	pF
Max output voltage		R _L =600Ω	-	2.0	-	V pk-pk
Max output current		R _L =22Ω	-	75	-	mA
Total Harmonic Distortion plus Noise	THD+N	$f_{\text{IN}}\text{=}1\text{kHz},$ BW=22Hz to 22kHz $R_{\text{L}}\text{=}600\Omega$	-	0.015	-	%
Output noise relative to full scale	SNR	A Weighted, Po=digital silence, $R_{\rm L}{=}600\Omega,$ BW=22Hz to 22kHz	-	-91	-	dB
Channel Separation (Crosstalk)	CS	f _{IN} =10kHz, analogue output set to maximum gain	-	-	-60	dB
Power Supply Rejection Ratio	PSRR	V_{npple} =200m V_{pk-pk} sinewave, 10kHz at VDD 3.1V \leq VDD \leq 3.6V, analogue output set to maximum gain	-	TBD	-	dB
Second Harmonic Level		1kHz sinewave, 1dB below full scale 600 Ω	-	<-95	-	dB
Third Harmonic Level		1kHz sinewave, 1dB below full scale 600 Ω	-	-95	-	dB

Audio Output, Speaker Output

²Input signal amplitudes are expressed as the differential voltages between the MIC_P and MIC_N terminals

Typical THD + N Relative to Full Scale

Full Scale Output, mV rms	600	Ω	22Ω		
	%	dB	%	dB	
10	0.180	-54.7	0.180	-54.7	
14	0.120	-58.2	0.120	-58.2	
20	0.090	-60.7	0.090	-60.7	
28	0.060	-64.2	0.062	-63.9	
40	0.046	-66.5	0.048	-66.1	
57	0.032	-69.7	0.036	-68.6	
80	0.025	-71.8	0.030	-70.2	
113	0.018	-74.6	0.024	-72.1	
160	0.015	-76.2	0.022	-72.9	
226	0.015	-76.2	0.020	-73.7	
320	0.015	-76.2	0.019	-74.2	
453	0.015	-76.2	0.019	-74.2	
640	0.014	-76.8	0.019	-74.2	
905	0.014	-76.8	0.019	-74.2	
1280	0.014	-76.8	0.022	-72.9	
1810	0.014	-76.8			



Power Consumption

Typical Average Current Consumption								
VDD=3.3V	Temperature = +20°C	Output Power	= 0dBm					
Mode			Average	Unit				
SCO connectio	n HV3 (30ms interval Sniff Mode) (Slave)	21	mA				
SCO connectio	n HV3 (30ms interval Sniff Mode) (Master)	21	mA				
SCO connectio	n HV3 (No Sniff Mode) (Slave)		28	mA				
SCO connectio	n HV1 (Slave)		42	mA				
SCO connectio	n HV1 (Master)		42	mA				
ACL data trans	fer 115.2kbps UART no traffic (M	laster)	5	mA				
ACL data trans	fer 115.2kbps UART no traffic (S	lave)	22	mA				
ACL data trans	fer 720kbps UART (Master or Sla	ave)	45	mA				
ACL data trans	fer 720kbps USB (Master or Slav	re)	45	mA				
ACL connection	n, Sniff Mode 40ms interval, 38.4	kbps UART	3.2	mA				
ACL connection	n, Sniff Mode 1.28s interval, 38.4	kbps UART	0.45	mA				
Parked Slave,	1.28s beacon interval, 38.4kbps l	JART	0.55	mA				
Standby Mode	(Connected to host, no RF activit	ty)	47	μΑ				
Reset (RESET	high or RESETB low)		15	μΑ				
DSP								
DSP core (inclu	uding PM memory access)							
Minimum (NOF	?)		0.25	mA/MIPS				
Maximum (MA	C)		0.65	mA/MIPS				
DSP memory a	ccess (DM1 or DM2)		0.15	mA/MIPS				
CODEC								
Microphone inp	outs and ADC / channel		0.85	mA				
DAC and louds	peaker driver, no signal / channe	1	1.4	mA				
Digital audio pr	ocessing subsystem		8	mA				

Peak current consumption								
VDD=3.3V Temperature = +20°C Output Power (max)= 7dBm								
	Mode		Тур	Unit				
Peak consumption during RF peaks			75	mA				



4 Radio Characteristics

VDD = 3.3V Temperature = 20 °C Frequency = 2.441GHz All measurements are based on the Bluetooth test specification.

Radio Cha	VDD = 3.3	8V	Те	mperature = +25°C		
		Min	Тур	Max	Bluetooth Specification	Unit
Operating frequency		2402	-	2480		MHz
Maximum RF transmit powe	er	7.8	8.6	9.9	0 to 20	dBm
	Frequency (GHz)				≤-70	dBm
Sensitivity at 0.1% BER	2.402	-	-85	-		
Sensitivity at 0.1% DER	2.441	-	-86	-		
	2.480	-	-85	-		
RF power control range		-	24	-	≥16	dB
RF power range control res	olution	2.2	4	4.4	-	dB
20dB bandwidth for modula	ted carrier	-	800	-	≤1000	kHz
Δf1avg .Maximum Modulati	on.	-	165	-	40 <f1avg<175< td=""><td></td></f1avg<175<>	
Δf2max .Minimum Modulati	on.	-	150	-	115	
∆f1avg/∆f2avg		-	0.98	-	≥0.80	-
Initial carrier frequency tolerance		-	10	-	±75	kHz
Drift Rate		-	8	-	≤20	KHz/50µs
Drift (single slot packet)		-	7	-	≤25	kHz
Drift (five slot packet)		-	8	-	≤40	kHz

Note:

The F2M03MLA has a maximum transmit power of +8dBm and is certified according to the Bluetooth v2.0 specification as a Class1 device. It is though possible to restrict the maximum transmit power to comply with either a Class2 or Class3 device upon configuration.

Bluetooth Specification

Class of device	Maximum transmit power
Class1	+20dBm
Class2	+4dBm
Class3	0dBm



5 Firmware versions

F2M03MLA is supplied with Bluetooth stack firmware, which runs on the internal RISC micro controller of the Bluetooth module. This chapter includes an overview of the different options for more in depth information please use separate firmware datasheets provided by Free2move.

All firmware versions are compliant with the Bluetooth specification v2.0. The F2M03MLA software architecture allows Bluetooth processing to be shared between the internal microcontroller and a host processor. Depending on application the upper layers of the Bluetooth stack (above HCI) can execute on-chip or on the host processor.

Running the upper stack on the F2M03MLA module reduces (or eliminates, in the case of a on module application) the need for host-side software and processing time.

The integration approach depends on the type of product being developed. For example, performance will depend on the integration approach adopted. Free2move is currently offering two categories of Bluetooth stack firmware for the F2M03MLA:

- Wireless Audio Headset (WAH) is Free2move's standard firmware for Headset applications. It is
 intended for applications that want to incorporate Headset functionality to be able to communicate
 with for example mobile phones. The firmware can be used either as stand-alone with a button
 interface as the only input to control the firmware or connected to another serial device (e.g.
 microcontroller) through the UART interface.
- Customised firmwares. Free2move have the possibility to customise firmwares for special customer applications.



5.1 Wireless Audio

Wireless Audio Headset (WAH) is Free2move's standard firmware for Headset applications. It is intended for applications that want to incorporate Headset functionality to be able to communicate with for example mobile phones. The firmware can be used either as stand-alone with a button interface as the only input to control the firmware or connected to another serial device (e.g. microcontroller) through the UART interface.

The current version (V. 2.00) includes the following Bluetooth profiles:

- A2DP (sink)
- AVRCP (controller)
- HFP 1.5 (headset)
- HSP (headset)
- SPP (slave)

Firmware running on the Free2move Bluetooth module		The connecting device is typically a mobile phone
Wireless Audio Headset	Direction	"Mobile phone"
A2DP (sink)	•	A2DP (source)
AVRCP (controller)	•>	AVRCP (target)
HFP 1.5 (headset)	▲ → →	HFP 1.5 (audio gateway)
HSP (headset)	→	HSP (audio gateway)
SPP (endpoint)	→	SPP (connecting)

Please look at the full datasheet for the Wireless Audio Headset firmware for more information regarding the functionality.

5.1.1 Supported hardware

The Wireless Audio Headset V. 2.00 firmware is currently supported on the following Free2move products:

• F2M03MLA Free2move Low power Bluetooth Multimedia module with Antenna (Article nr. F2M03MLA-S03)



5.2 Customised firmwares

Customised firmwares can be made upon request. Free2move have the possibility to produce modules with customer specific settings of the Wireless Audio Headset firmware (most applicable in large production volumes).

Free2move can also provide special firmwares for customer applications.

Please consult your reseller for more information about customised firmwares and special requirements.

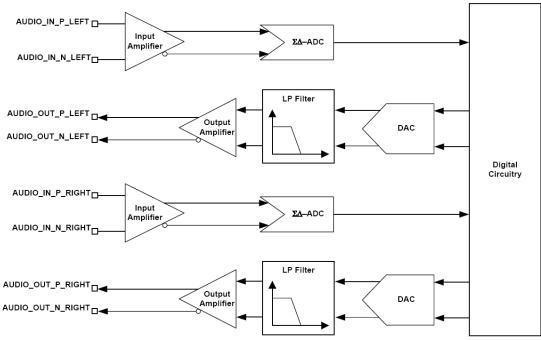


6 Device terminal description

6.1 Stereo Audio Interface

The main features of the interface are:

- Stereo and mono analogue input for voice band and audio band
- Stereo and mono analogue output for voice band and audio band
- Support for stereo digital audio bus standards such as I²S
- Support for IEC-60958 standard stereo digital audio bus standards i.e. S/PDIF and AES3/EBU
- Support for PCM interfaces including PCM master CODECs that require an external system clock



Stereo CODEC Audio input and output stages

The stereo audio CODEC uses a fully differential architecture in the analogue signal path, which results in low noise sensitivity and good power supply rejection while effectively doubling the signal amplitude.

Important Note:

To avoid any confusion with respect to stereo operation this datasheet with respect to hardware explicitly states which is the left and right channel for audio input and output.

For mono operation F2M03MLA uses the left channel for standard mono operation for audio input and output.



6.1.1 ADC

The ADC consists of two second order Sigma Delta converters allowing two separate channels that are identical in functionality.

ADC Sample Rates

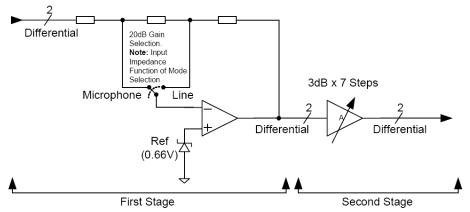
Each ADC supports the following sample rates:

- 8kHz
- 11.025kHz
- 16kHz
- 22.05kHz
- 24kHz
- 32kHz
- 44.1kHz

ADC Gain

The ADC contains two gain stages for each channel, an analogue and a digital gain stage. The digital gain stage has a range of -24 dB to +21.5 dB.

The ADC analogue amplifier is a two stage amplifier. The first stage of the analogue amplifier is responsible for selecting the correct gain for either microphone input or line input and therefore has two gain settings, one for the microphone and one for the line input. In simple terms the first stage amplifier has a selectable 20dB gain stage for the microphone and this creates the dual programmable gain required for the microphone or the line input. The equivalent block diagram for the two stage is shown in the figure below.



First and second stage of ADC analogue amplifier block diagram

The second stage of the analogue amplifier has a programmable gain with seven individual 3dB steps. In simple terms, by combining the 20dB gain selection of the microphone input with the seven individual 3dB gain steps, the overall range of the analogue amplifier is approximately -4dB to 40dB. The overall gain setting of the ADC is a combined function of the digital and analogue amplifier settings, so that the fullscale range of the input to the ADC is kept to approximately 400mV rms.



6.1.2 DAC

The DAC consists of two second order Sigma Delta converters allowing two separate channels that are identical in functionality.

DAC Sample rates

Each DAC supports the following samples rates:

- 48kHz
- 44.1kHz
- 32kHz
- 24kHz
- 22.050kHz
- 16kHz
- 11.025kHz
- 8kHz

DAC Gain

The DAC contains two gain stages for each channel, a digital and an analogue gain stage. The digital gain stage has a programmable selection value in the range of –24dB to 21.5dB.

The DAC analogue amplifier unlike the ADC is a single stage amplifier with the same structure as the second stage of the ADC analogue amplifier. The structure of the DAC analogue amplifier is similar to the second stage of the ADC analogue amplifier.

The overall gain setting of the DAC is a combined function of the digital and analogue amplifier settings, therefore for a 1V rms nominal digital output signal from the digital gain stage of the DAC, the approximate output values of the analogue amplifier of the DAC is in the range of 0dB to -21dB.

6.1.3 Mono Operation

Mono operation is single channel operation of the stereo CODEC. The left channel represents the single mono channel for audio in and audio out. In mono operation the right channel is auxiliary mono channel that may be used in dual mono channel operation.



6.2 PCM CODEC Interface

Pulse Code Modulation (PCM) is the standard method used to digitise audio (particulary voice) for transmission over digital communication channels. Through its PCM interface, F2M03MLA has hardware support for continual transmission and reception of PCM data, thus reducing processor overhead for wireless headset and other audio applications. F2M03MLA offers a bi-directional digital audio interface that routes directly into the baseband layer of the on-chip firmware. It does not pass through the HCI protocol layer.

Hardware on F2M03MLA allows the data to be sent to and received from a SCO connection. Up to three SCO connections can be supported by the PCM interface at any one time⁽¹⁾

F2M03MLA can operate as the PCM interface Master generating an output clock of 128, 256 or 512kHz. When configured as PCM interface slave it can operate with an input clock up to 2048kHz. F2M03MLA is compatible with a variety of clock formats, including Long Frame Sync, Short Frame Sync and GCI timing environments.

It supports 13 or 16-bit linear, 8-bit µ-law or A-law companded sample formats at 8ksamples/s and can receive and transmit on any selection of three of the first four slots following PCM_SYNC. The PCM configuration options are enabled by firmware settings (contact Free2move).

F2M03MLA interfaces directly to PCM audio devices includes the following:

- WM8731 Audio CODEC from Wolfson Micro
- Qualcomm MSM 3000 series and MSM 5000 series CDMA baseband devices
- OKI MSM7705 four channel A-law and µ-law CODEC
- Motorola MC145481 8-bit A-law and µ-law CODEC
- Motorola MC145483 13-bit linear CODEC
- Winbond W681360R 13-bit linear CODEC
- STW 5093 and 5094 14-bit linear CODECs
- F2M03MLA is also compatible with the Motorola SSI^TM interface

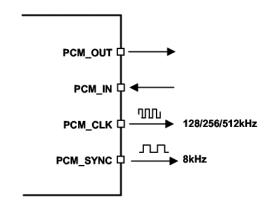
Note:

¹⁾ Subject to firmware support, contact Free2move for current status.



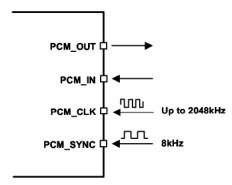
6.2.1 PCM Interface Master/Slave

When configured as the Master of the PCM interface, F2M03MLA generates PCM_CLK and PCM_SYNC.



F2M03MLA as PCM Interface Master

When configured as the Slave of the PCM interface, F2M03MLA accepts PCM_CLK rates up to 2048kHz

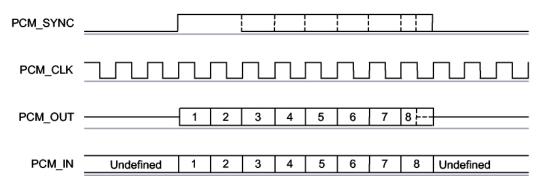


F2M03MLA as PCM Interface Master



6.2.2 Long Frame Sync

Long Frame Sync is the name given to a clocking format that controls the transfer of PCM data words or samples. In Long Frame Sync, the rising edge of PCM_SYNC indicates the start of the PCM word. When F2M03MLA is configured as PCM Master, generating PCM_SYNC and PCM_CLK, then PCM_SYNC is 8-bits long. When F2M03MLA is configured as PCM Slave, PCM_SYNC may be from two consecutive falling edges of PCM_CLK to half the PCM_SYNC rate (i.e., 62.5µs) long.

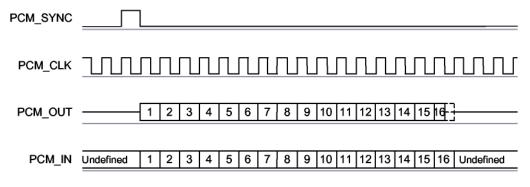


Long Frame Sync (Shown with 8-bit Companded Sample)

F2M03MLA samples PCM_IN on the falling edge of PCM_CLK and transmits PCM_OUT on the rising edge. PCM_OUT may be configured to be high impedance on the falling edge of PCM_CLK in the LSB position or on the rising edge.

6.2.3 Short Frame Sync

In Short Frame Sync the falling edge of PCM_SYNC indicates the start of the PCM word. PCM_SYNC is always one clock cycle long.



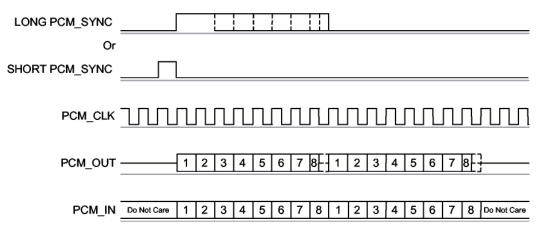
Short Frame Sync (Shown with 16-bit Sample)

As with Long Frame Sync, F2M03MLA samples PCM_IN on the falling edge of PCM_CLK and transmits PCM_OUT on the rising edge. PCM_OUT may be configured to be high impedance on the falling edge of PCM_CLK in the LSB position or on the rising edge



6.2.4 Multi-Slot Operation

More than one SCO connection over the PCM interface is supported using multiple slots. Up to three SCO connections can be carried over any of the first four slots.



Multi-slot Operation with Two Slots and 8-bit Companded Samples

6.2.5 GCI Interface

F2M03MLA is compatible with the General Circuit Interface, a standard synchronous 2B+D ISDN timing interface. The two 64Kbps B channels can be accessed when this mode is configured. In the GCI interface two clock cycles are required for each bit of the voice sample. The voice sample format is 8-bit companded. As for the standard PCM interface up to 3 SCO connections can be carried over the first four slots.

PCM_SYNC																		
PCM_CLK	11		ΩΛ	ЛЛ	ЛЛ	ЛЛ	ЛЛ	Л	ſΛ	ЛЛ	ЛЛ		ЛЛ	ЛЛ				
PCM_OUT		1	2	3	4	5	6	7	8	- 1	2	3	4	5	6	7	8]
PCM_IN	Do Not Care	1	2	3	4 B1 (5 Chanr	6	7	8	1	2	3	4 B2 C	5	6	7	8	Do Not Care
					ы	JICIII							52 (n di li				



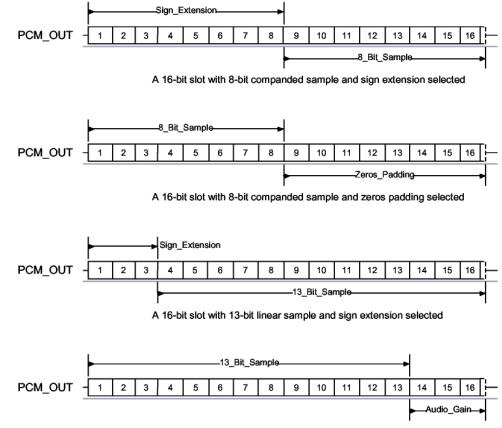
The start of frame is indicated by PCM SYNC and runs at 8kHz. With F2M03MLA in Slave mode, the frequency of PCMCLK can be up to PCM_SYNC In order to configure the PCM interface to work in GCI mode it is necessary to have the correct firmware support (contact Free2move)



6.2.6 Slots and Sample Formats

F2M03MLA can receive and transmit on any selection of the first four slots following each sync pulse. Slot durations can be either 8 or 16 clock cycles. Durations of 8 clock cycles may only be used with 8-bit sample formats. Durations of 16 clocks may be used with 8, 13 or 16-bit sample formats.

F2M03MLA supports 13-bit linear, 16-bit linear and 8-bit µ-law or A-law sample formats. The sample rate is 8ksamples/s. The bit order may be little or big endian. When 16-bit slots are used, the 3 or 8 unused bits in each slot may be filled with sign extension, padded with zeros or a programmable 3-bit audio attenuation compatible with some Motorola CODECs.



A 16-bit slot with 13-bit linear sample and audio gain selected

6.2.7 Additional Features

F2M03MLA has a mute facility that forces PCM_OUT to be 0. In Master mode, PCM_SYNC may also be forced to 0 while keeping PCM_CLK running (which some CODECS use to control power-down)



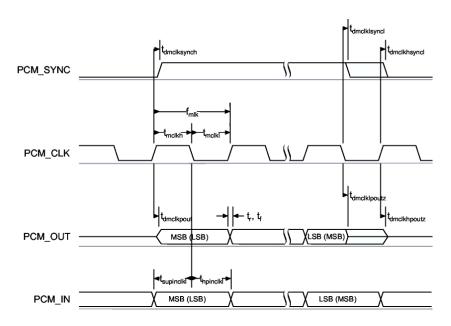
6.2.8 PCM Timing Information

PCM Master Timing

Symbol	Para	meter	Min ⁽¹⁾	Тур	Max ⁽²⁾	Unit
£	PCM_CLK	4MHz DDS generation	-	128 256 512	-	kHz
f _{mclk} frequency	48MHz DDS generation	2.9		-	kHz	
-	PCM_SYNC frequenc	у	-	8		kHz
t _{mclkh} (1)	PCM_CLK high 4	MHz DDS generation	980	-	-	ns
t _{mclk} I ⁽¹⁾		MHz DDS generation	730	-		ns
-		MHz DDS generation			21	Ns pk-pk
t _{dmclksynch}	Delay time from PCM PCM_SYNC high	_CLK high to	-	-	20	ns
t _{dmclkpout}	Delay time from PCM PCM_OUT	_CLK high to valid	-	-	20	ns
t _{dmclklsyncl}	Delay time from PCM PCM_SYNC low (Long only)		-	-	20	ns
t _{dmclkhsyncl}	Delay time from PCM PCM_SYNC low	_CLK high to	-	-	20	ns
t _{dmclklpoutz}	Delay time from PCM PCMOUT high imped		-	-	20	ns
t _{dmclkhpoutz}	Delay time from PCM CLK high to PCMOUT high impedance		-	-	20	ns
t _{supinciki}	Set-up time for PCM_ PCM_CLK low	IN valid to	30	-	-	ns
t _{hpinclkl}	Hold time for PCM_CI invalid	LK low to PCM_IN	10	-	-	ns

Note: ⁽¹⁾ Assumes normal system clock operation. Figures will vary during low power modes, when system clock speeds are reduced.





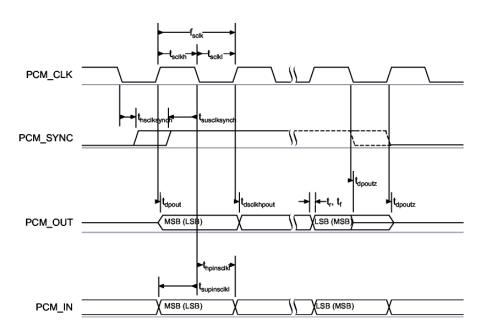
PCM Master Timing

PCM Slave Timing

Symbol	Parameter	Min	Тур	Max	Unit
f _{sclk}	PCM clock frequency (Slave mode: input)	64	-	2048	kHz
f _{sclk}	PCM clock frequency (GCI mode)	128	-	4096	kHz
t _{sciki}	PCM_CLK low time	200	-	-	ns
t _{sclkh}	PCM_CLK high time	200	-	-	ns
t _{hsclksynch}	Hold time from PCM_CLK low to PCM_SYNC high	30	-	-	ns
t _{susciksynch}	Set-up time for PCM_SYNC high to PCM_CLK low	30	-	-	ns
t _{dpout}	Delay time from PCM_SYNC or PCM_CLK whichever is later, to valid PCM_OUT data (Long Frame Sync only)	-	-	20	ns
t _{dsclkhpout}	Delay time from CLK high to PCM_OUT valid data	-	-	20	ns
t _{dpoutz}	Delay time from PCM_SYNC or PCM_CLK low, whichever is later, to PCM_OUT data line high impedance	-	-	20	ns
t _{supinsclkl}	Set-up time for PCM_IN valid to CLK low	30	-	-	ns
t _{hpinsclkl}	Hold time for PCM_CLK low to PCM_IN invalid	30	-		ns
tr	Edge rise time (CI = 50 pF, 10-90 %)	-	-	15	ns
T _f	Edge fall time (CI = 50 pF, 10-90 %)	-	-	15	ns



Low power Multimedia Bluetooth™ Module with antenna F2M03MLA Datasheet



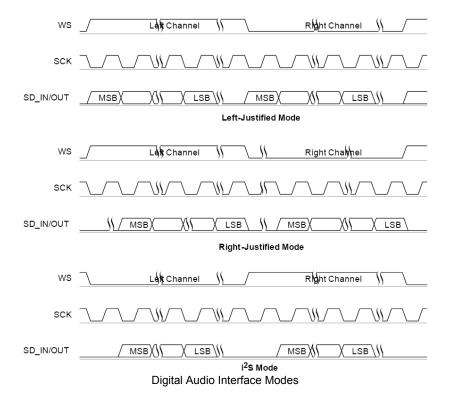
PCM slave timing

FREE2MOVE

Low power Multimedia Bluetooth™ Module with antenna F2M03MLA Datasheet

6.2.9 Digital Audio Bus

The digital audio interface supports the industry standard formats for I^2S , left-justified (LJ) or right-justified(RJ)¹. The interface shares the same pins as the PCM interface and the timing diagram is shown in the figure below.



The internal representation of audio samples within F2M03MLA is 16-bit and data on SD_OUT is limited to 16-bit per channel. On SD_IN, if more than 16-bit per channel is present will round considering the 17th bit.

SCK typically operates 64 x WS frequency and cannot be less than 36 x WS.

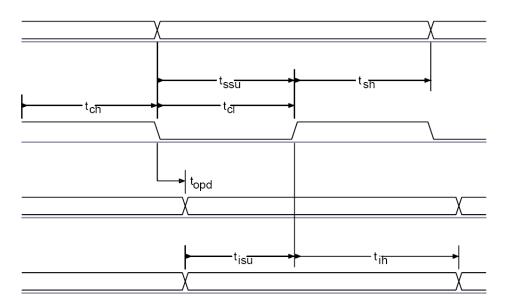
Note:

¹ Subject to firmware support, contact Free2move for more information.



Digital Audio Interface Slave timing

Symbol	Parameter	Min	Тур	Мах	Unit
-	SCK Frequency	-	-	6.2	MHz
-	WS Frequency	-	-	96	kHz
t _{ch}	SCK high time	-	-	-	ns
t _{cl}	SCK low time	-	-	-	ns
t _{opd}	SCK to SD_OUT delay	-	-	-	ns
t _{ssu}	WS to SCK high set-up time	-	-	-	ns
t _{sh}	WS to SCK high hold time	-	-	-	ns
t _{isu}	SD_IN to SCK high set-up time	-	-	-	ns
t _{ih}	SD_IN to SCK high hold time	-	-	-	ns

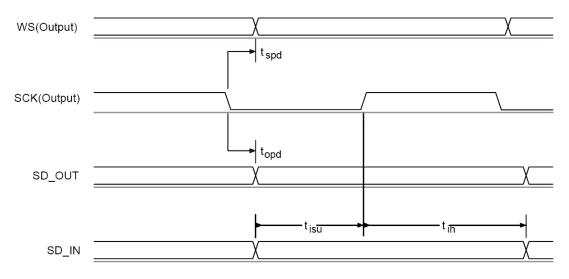


Digital Audio Interface Slave Timing



Digital Audio	Interface	Master	timing
---------------	-----------	--------	--------

Symbol	Parameter	Min	Тур	Мах	Unit
-	SCK Frequency	-	-	6.2	MHz
-	WS Frequency	-	-	96	kHz
t _{opd}	SCK to SD_OUT delay	-	-	-	ns
T _{spd}	SCK to WS delay	-	-	-	ns
t _{isu}	SD_IN to SCK high set-up time	-	-	-	ns
t _{ih}	SD_IN to SCK high hold time	-	-	-	ns



Digital Audio Interface Master Timing



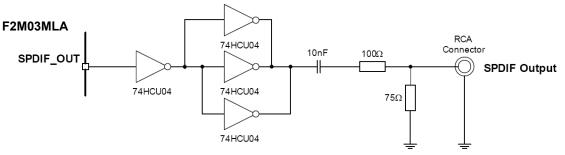
6.2.10 IEC 60958 Interface

The IEC 60958 interface is a digital audio interface that uses bi-phase coding to minimise the DC content of the transmitted signal and allows the receiver to decode the clock information from the transmitted signal. The IEC 60958 specification is based on the two industry standards AES/EBU and the Sony and Philips interface specification SPDIF. The interface is compatible with IEC 60958-1, IEC 60958-3 and IEC 60958-4¹.

Note:

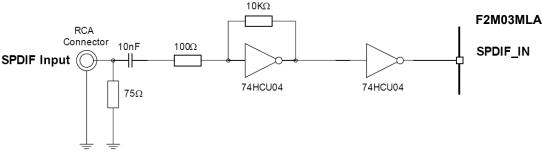
¹ Subject to firmware support, contact Free2move for information.

The SPDIF interface signals are SPDIF_IN and SPDIF_OUT and are shared on the PCM interface pins. The input and output stages of the SPDIF pins can interface either 75 Ω coaxial cable with an RCA connector or there is an option to use an optical link that uses Toslink optical components. Typical output and input stage interfaces for the coaxial and alternative optical solution interface is shown in the figures below.



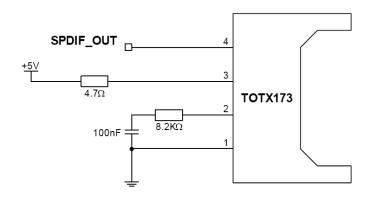
Example circuit for SPDIF Interface with coaxial output

Note: The 100Ω and 75Ω resistors are dependent on the supply voltage and therefore subject to change.

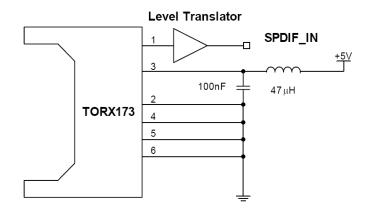


Example circuit for SPDIF Interface with coaxial input





Example circuit for SPDIF interface with optical output



Example circuit for SPDIF interface with optical input

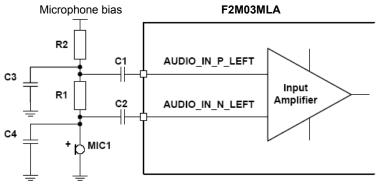
6.2.11 Audio Input Stage

The input stage of F2M03MLA consists of a low noise input amplifier, which receives its analogue input signal from pins AUDIO_IN_P_LEFT and AUDIO_IN_N_LEFT to a second-order Σ - Δ ADC that outputs a 4MBit/sec single-bit stream into the digital circuitry. The input can be configured to be either single ended or fully differential. It can be programmed for either microphone or line input and has a 3-bit digital gain setting of the input-amplifier in 3dB steps to optimize it for the use of different microphones.



6.2.12 Microphone Input

The audio-input is intended for use from $1\mu V@94dB$ SPL to about $10\mu V@94dB$ SPL. With biasing-resistors R1 and R2 equal to $1k\Omega$, this requires microphones with sensitivity between about -40dBV/Pa and -60dBV/Pa. The microphone for each channel should be biased as shown in the figure below.

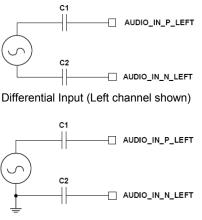


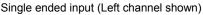
Microphone Biasing (Left Channel Shown)

The input impedance at AUDIO_IN_N_LEFT, AUDIO_IN_P_LEFT, AUDIO_IN_N_RIGHT and AUDIO_IN_P_RIGHT is typically $20k\Omega$. C1 and C2 should be 47nF. R1 sets the microphone load impedance and is normally in a range of 1 to $2 k\Omega$. R2, C3 and C4 improve the supply rejection by decoupling supply noise from the microphone. Values should be selected as required in the specification. R2 may be connected to a convenient supply (typically VDD).

6.2.13 Line Input

If the input gain is set to less than 21dB F2M03MLA automatically selects line input mode. In this mode the input impedance at AUDIO_IN_N_LEFT, AUDIO_IN_P_LEFT, AUDIO_IN_N_RIGHT and AUDIO_IN_P_RIGHT are increased to $130k\Omega$ typically. In line-input mode, the full-scale input signal is about 400mV rms. The figures below show two circuits for line input operation and show connections for either differential or single ended inputs.







6.2.14 Output Stage

The output digital circuitry converts the signal from 16-bit per sample, linear PCM of variable sampling frequency to an 8 MBits/sec bit stream, which is fed into the analogue output circuitry.

The output circuit comprises a digital to analogue converter with gain setting and output amplifier. Its class-AB output-stage is capable of driving a signal on both channels of up to 2V pk-pk- differential into a load of 32 Ω and 500pF with a typical THD+N of -74dBc. The output is available as a differential signal between AUDIO_OUT_N_LEFT and AUDIO_OUT_P_LEFT for the left channel as shown in Figure 8.45; and between AUDIO_OUT_N_RIGHT and AUDIO_OUT_P_RIGHT for the right channel. The output is capable of driving a speaker directly if its impedance is at least 16 Ω if only one channel is connected or an external regulator is used.

AUDIO_OUT_P_LEFT	7,
	Ŵ
AUDIO_OUT_N_LEFT	

The gain of the output stage is controlled by a 3-bit programmable resistive divider, which sets the gain in steps of approximately 3dB.

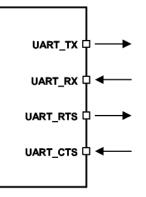
The single bit stream from the digital circuitry is low pass filtered by a second order bi-quad filter with a pole at 20kHz. The signal is then amplified in the fully differential output stage, which has a gain bandwidth of typically 1MHz. It uses its high open loop gain in the closed loop application circuit to achieve low distortion while operating with low standing current.

Speaker output (Left channel shown)



6.3 UART Interface

The F2M03MLA Bluetooth module's Universal Asynchronous Receiver Transmitter (UART) interface provides a simple mechanism for communicating with other serial devices using the RS232 standard⁽¹⁾.



Universal Asynchronous Receiver

Four signals are used to implement the UART function, as shown in the figure above. When F2M03MLA is connected to another digital device, UART_RX and UART_TX transfer data between the two devices. The remaining two signals, UART_CTS and UART_RTS, can be used to implement RS232 hardware flow control where both are active low indicators. All UART connections are implemented using CMOS technology and have signalling levels of 0V and VDD. UART configuration parameters, such as Baud rate and packet format, are set by Free2move firmware.

Note:

In order to communicate with the UART at its maximum data rate using a standard PC, an accelerated serial port adapter card is required for the PC.

⁽¹⁾ Uses RS232 protocol but voltage levels are 0V to VDD, (requires external RS232 transceiver IC)

Parameter		Possible Values
Baud Rate	Minimum	1200 Baud (≤2%Error)
		9600 Baud (≤1%Error)
	Maximum	1.5MBaud (≤1%Error)
Flow Control		RTS/CTS or None
Parity		None, Odd or Even
Number of Stop Bits		1 or 2
Bits per channel		8

Possible UART Settings



The UART interface is capable of resetting the Free2move module upon reception of a break signal. A Break is identified by a continuous logic low on the UART_RX terminal, as shown in figure below. If tBRK is longer than a special value, defined by the Free2move firmware a reset will occur. This feature allows a host to initialise the system to a known state. Also, the F2M03MLA can emit a Break character that may be used to wake the Host. The above capabilities are not supported in the standard firmware, please contact Free2move for more information.



Break signal



6.4 Serial Peripheral Interface

F2M03MLA is a slave device that uses terminals SPI_MOSI, SPI_MISO, SPI_CLK and SPI_CSB. This interface is used for program emulation/debug and IC test. It is also the means by which the F2M03MLA flash may be programmed, before any 'boot' program is loaded.

The SPI signals should be routed out from the module if you need to upgrade the firmware on the module in the future when the module is already soldered.

Note:

The designer should be aware that no security protection is built into the hardware or firmware associated with this port, so the terminals should not be permanently connected in a PC application. This interface is not a user interface and only used for initial download and configuration of the firmware for the module.

6.5 I²C Interface

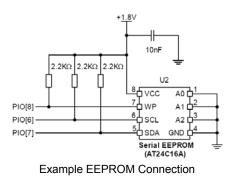
PIO[8:6] can be used to form a master I2C interface. The interface is formed using software to drive these lines. Therefore, it is suited only to relatively slow functions such as driving a dot matrix liquid crystal display (LCD), keyboard scanner or EEPROM.

Notes:

The 2 C interface is controlled by firmware specific settings. Please see specific firmware datasheet for information PIO lines need to be pulled-up through 2.2k: resistors.

PIO[7:6] dual functions, UART bypass and EEPROM support, therefore, devices using an EEPROM cannot support UART bypass mode.

For connection to EEPROMs, contact Free2move for information about devices that are currently supported.





6.6 PIOs

The F2M03MLA have 8 programmable general-purpose I/O ports PIO[11:6, 1:0] and one analog I/O port AIO[0]. The F2M03MLA also has one digital to analog port AUX_DAC. PIO lines can be configured through software to have either weak or strong pull-ups or pull-downs.

All PIO lines are configured as inputs with weak pull-downs at reset.

AIO[0] functions available via this pin include an 8-bit ADC but can also be used as general-purpose I/O line. Typically the AIO[0] is used for battery voltage measurement. The voltage range for AIO[0] is constrained by the internal analogue supply voltage which is 1.8V.

The AUX_DAC is a 8-bit Digital to Analog Conveter used for customer specific applications. The voltage range is from 0V to VDD.

Note:

The PIO, AIO and AUX_DAC lines are controlled by firmware specific settings. Please see specific firmware datasheet for information about the PIOs used!

6.6.1 General-purpose I/O lines

PIO[0]

I/O terminal with programmable strength internal pull-up/down.

PIO[1]

I/O terminal with programmable strength internal pull-up/down.

PIO[6]

I/O terminal with programmable strength internal pull-up/down.

PIO[7]

I/O terminal with programmable strength internal pull-up/down.

PIO[8]

I/O terminal with programmable strength internal pull-up/down.

PIO[9]

I/O terminal with programmable strength internal pull-up/down.

PIO[10]

I/O terminal with programmable strength internal pull-up/down.

PIO[11]

I/O terminal with programmable strength internal pull-up/down.

6.6.2 Analog I/O lines

AIO[0]

Programmable input/output line also possible to use as digital I/O

AUX_DAC

Digital to Analog output line.



6.7 Power supply

The power supply for the F2M03MLA should be chosen carefully. Bad power supply can reduce the performance and may damage the module. Please use the recommended voltage regulator or consult Free2move if using another regulator. It is also essential to use a proper reset circuit to the module for correct operation.

6.7.1 Voltage regulator

The F2M03MLA has one power supply, +VCC.

The voltage supplied should have low noise, less than 10mV rms between 0 and 10MHz. The transient response of the regulator is also important. At the start of a Bluetooth packet, power consumption will jump to high levels. The regulator should have a response time of 20µs or less; it is essential that the power rail recovers quickly.

Recommended voltage regulator: XC6209B332MR from Torex or TPS73633DBVTG4 from Texas Instrument

6.7.2 Reset

The F2M03MLA has an active low reset (pin nr: 38). The reset pin MUST be connected to either a resetcircuit (voltage monitor) such as the TC1270ASVRCTR, MAX811S, DS1818 or using an I/O from a microcontroller. Reset cannot be done with a R-C network. It is recommended to used one of the reset circuits mentioned above. Special considerations must be taken when using an I/O from a microcontroller; a pull-down resistor (typically 1.8k Ω) must be placed on the I/O-line.

It is recommended that RESET is applied for a period greater than 5ms.

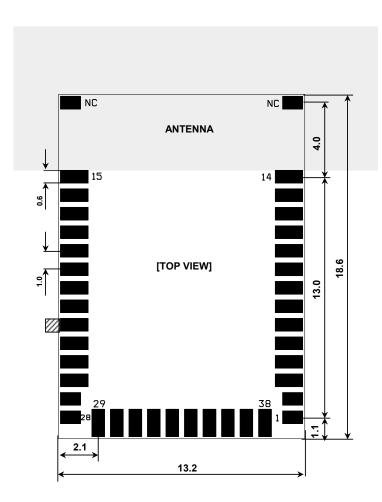
At reset the digital I/O pins are set to inputs for bi-directional pins and outputs are tristated. The PIOs have weak pull-downs.



7 Application information

7.1 Recommended land pattern

All dimensions are in [mm]



F2M03MLA

Solder pad

- Recommended extended pad for manual soldering (apply for all solder pads)
- Restricted area for ground planes or other components
- Pad size: 0.6x1.4 and 0.6x0.8mm,
- Solder mask opening: Pad size + 0.1mm
- Pitch: 1.0mm

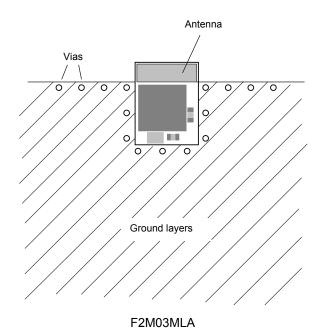


7.2 Layout guidelines

The module uses bottom pads for soldering optimized for an automatic solder line. It is also possible to solder the module manually by using hot air soldering. For manual soldering solder pads may in some situation be made slightly larger to allow easier heating process.

To achieve good RF performance it is recommended to place ground plane(s) beneath the module but not under the antenna. The ground planes should be connected with vias surrounding the module. Except from the ground plane it is preferable that there are as few components and other material as possible nearby the antenna. Free air is the best surrounding for the antenna.

All GND pads must be connected directly to a flooded ground-plane. If more then one ground layer is used then make a good connection between them using many via holes. +VCC should be connected to the voltage regulator using a wide trace.

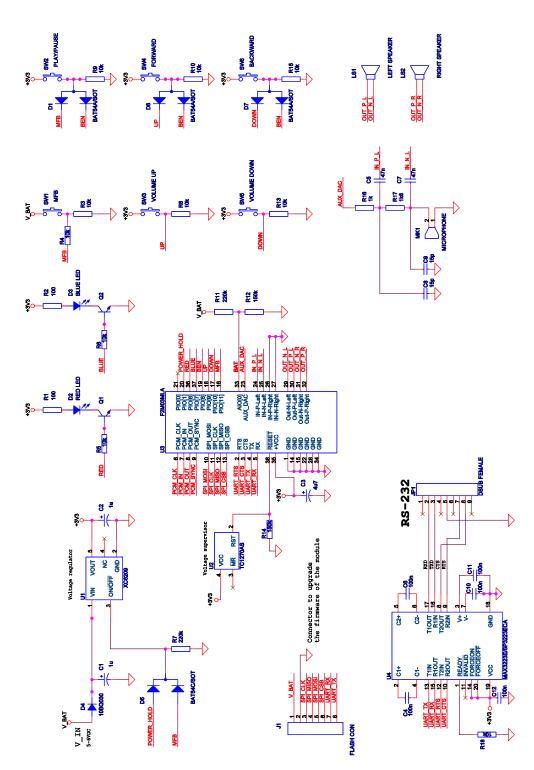




7.3 Typical application schematic



Low power Multimedia Bluetooth™ Module with antenna F2M03MLA Datasheet



Typical application schematic for F2M03MLA when using the Wireless Audio Headset firmware



Package information 8

F2M03MLA

Physical size [mm]: Length: 18.6 Width: 13.2

Height: 2.1

Weight: 1.2g



9 Certifications

9.1 Bluetooth

F2M03MLA has passed the Bluetooth Qualification/Certification process as specified within the Bluetooth Specifications and as required within the PRD 2.0.

QDID: B012539

9.2 CE

F2M03MLA complies with the requirements of R&TTE Directive 1999/5/CE, the European Community Directive 73/23/EEC and 93/68/EEC.

- EN 300 328
- EN 301 489-1/-17
- EN 60950



9.3 FCC

FCC-B Radio Frequency Interference Statement

This deceive has been tested and found to comply with the limits for a Class-B digital device, pursuant to part 15 of the FCC rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in commercial environment. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used according with the instruction manual, may cause harmful interference to radio communication. Operation of this equipment in a residential area is likely to cause harmful interference, in which case the user will be required to correct the interference at his own expense.

Notice1

The changes or modifications not expressly approved by the party responsible for the compliance could void the user's authority to operate the equipment.

Notice 2

Shielded interface cables an A.C. power cord, if any, must be used in order to comply with the emission limits.

Notice 3

This modular transmitter uses an electronic display of the FCC identification number, the information must be readily accessible on the device in which it is installed. The FCC ID can be read from the UART of the device.

UART Settings:

Baud rate: 38400bps Data bits: 8 Parity: None Stop bits: 1

Send command: "VERSION" (ASCII characters) over the UART and the module will respond with software, hardware information and the FCC ID.

FCC ID R47F2M03MLA

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) This device must accept any interference received, including interference that may cause undesired operation.

If the module is installed inside another device, then the outside of the device into which the module is installed must display a label referring to the enclosed module. This exterior label can use wording such as the following: "Contains FCC certified transmitter module(s)."

Any similar wording that expresses the same meaning may be used.



10 RoHS and WEEE Statement

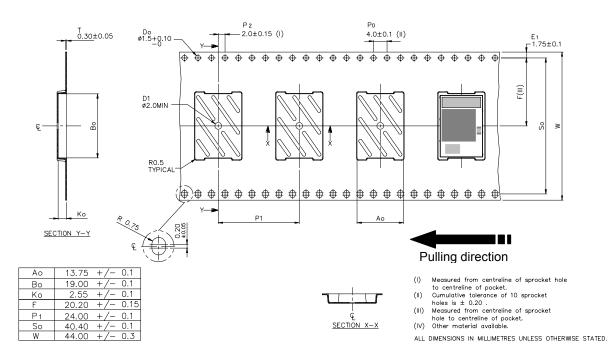
F2M03MLA meets the requirements of Directive 2002/95/EC of the European Parliament and of the Council on the Restriction of Hazardous Substance (RoHS).

F2M03MLA also meet the requirements of Directive 2002/96/EG -Waste Electrical and Electronic Equipment (WEEE).



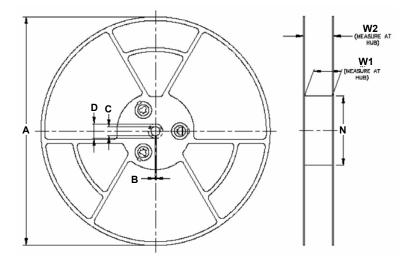
11 Tape and Reel information

11.1 Package Tape dimensions



11.2 Reel dimensions

330.0 max
1.5 min
13.0±0.2
20.2 min
100.0
44.4 +2.0 -0.0
50.4 max





12 Ordering information

The F2M03MLA is available for delivery in volumes.

Part nr:	Description
F2M03MLA-S03	Low power Bluetooth Multimedia module with antenna and Wireless Audio Headset firmware (HSP, HFP, A2DP, AVRCP and SPP)

Please visit our website: www.free2move.net for more information about local distributors and dealers.



13 Document history

Date	Revision	Reason for Change
OCTOBER 2007	с	Minor changes, added new information about Wireless Audio Headset.
JUNE 2007	b	Added information about certification and minor other changes in the document.
JAN 2007	а	Original Publication of this document.

F2M03MLA Datasheet

Datasheet_F2M03MLA_rev_c.pdf

Last revision change October 2007



14 Acronyms and definitions

Bluetooth A set of technologies providing audio and data transfer over short-range radio ACL Asynchronous Connection-Less. A Bluetooth data packet. AC Atternating Current Alaw Audio encoding standard API Application Programming Interface BCSP BlueCore TM Serial Protocol BER Bit Error Rate. Used to measure the quality of a link C/I Carrier Over Interferer CMOS Complementary Metal Oxide Semiconductor CODEC Coder Decoder CPU Central Processing Unit CQDDR Channel Quality Driven Data Rate CTS Clear to Send CVSD Continuous Variable Stope Delta Modulation DAC Digital to Analogue Converter GCI General Circuit Interface. GCI General Circuit Interface HCI Host Controller Interface HCI Header Value ISDN Integrated Services Digital Network ISDN Integrated Services Digital Network ISM Industrial, Scientific and Medical Kasamples/s Kilosampl	Term:	Definition:	
AC Atternating Current Aca Atternating Current Arlaw Audio encoding standard API Application Programming Interface BCSP BlueCore™ Serial Protocol BER Bit Error Rate. Used to measure the quality of a link C/I Carrier Over Interferer CMOS Complementary Metal Oxide Semiconductor CODEC Coder Interferer CMOS Complementary Metal Oxide Semiconductor CQDDR Charnel Ouality Driven Data Rate CTS Clear to Send CVSD Continuous Variable Slope Delta Modulation DAC Digital to Analogue Converter dBm Decides relative to InWW OC Direct Current DFU Derive Firmware Upgrade GCI General Circuit Interface. Standard synchronous 2B+D ISDN timing interface HGI Host Controller Interface HV Header Value ISDN Integrated Services Digital Network ISM Industrial, Scientific and Medical ksamples/s kilosamples per second L2CAP Logical Link Control and Adaptation Protocol (protocol layer)			
AC Alternating Current Araw Audio encoding standard API Application Programming Interface BCSP BlueCore TM Serial Protocol BER Bit Error Rate. Used to measure the quality of a link C/1 Carrier Over Interferer CMOS Complementary Metal Oxide Semiconductor CODEC Coder Decoder CPU Central Processing Unit CQDDR Channel Quality Driven Data Rate CTS Citer to Send CVSD Continuous Variable Stope Delta Modulation DAC Digital to Analogue Converter dBm Decibe's relative to TmW DFU Dericet Current DFU Dericet Cirrent Interface Host Application's microcontroller Host Application's microcontroller Host Application's microcontroller Host Application's microcontroller Host Industrial, Scientific and Medical Kasmples/s kilosamples per second L2CAP Logical Link Controller Least-Significant Bit			
Alaw Audio encoding standard API Application Programming Interface BCSP ButeCore™ Serial Protocol BER Bit Error Rate: Used to measure the quality of a link C/I Carrier Over Interferer CMOS Complementary Metal Oxide Semiconductor CODEC Coder Decoder CPU Central Processing Unit CQDDR Channel Quality Driven Data Rate CTS Clear to Send CVSD Continuous Variable Slope Delta Modulation DAC Digital to Analogue Converter dBm Declose Iralway to Lugrade GCI General Circuit Interface. Standard synchronous 2B+D ISDN timing interface HGI Host Controller Interface Host Application's microcontroller Host Application's microcontroller Host Application's microcontroller HV Header Value ISDN Integrated Services Digital Network ISM Industrial, Scientific and Medical Kasamples/s kilosamples per second L2CAP Logical Luck Control and Adaptation Protocol (protocol layer) LC Link Cont	AC		
API Application Programming Interface BCSP BlueCore [™] Serial Protocol BER Bit Error Rate. Used to measure the quality of a link C/I Carrier Over Interferer CMOS Complementary Metal Oxide Semiconductor CODEC Coder Decoder CPU Central Processing Unit CODDR Channel Quality Driven Data Rate CTS Clear to Send CVSD Continuous Variable Slope Delta Modulation DAC Digital to Analogue Converter dBm Decibels relative to 1mW DC Direct Current DFU Device Firmware Upgrade GCI General Circuit Interface. Standard synchronous 2B+D ISDN timing interface HOI Host Controller Interface Host Application's microcontroller Host Application's microcontroller Host Application's microcontroller Host Integrade Services Digital Network ISDN Integrade Services Digital Network IsSM Industrial, Scientific and Medical kasamples/s kilosamples per second			
BESP BiteCore™ Serial Protocol BER Bit Error Rate. Used to measure the quality of a link C/1 Carrier Over Interferer CMOS Complementary Metal Oxide Semiconductor CODEC Coder Decoder CPU Central Processing Unit CQDDR Channel Quality Driven Data Rate CTS Clear to Send CVSD Continuos Variable Stope Delta Modulation DAC Digital to Analogue Converter dBm Decibels relative to 1mW DC Direct Current DFU Device Firmware Upgrade GCI General Circuit Interface. Host Application's microcontroller Host Application's microcontroller Host Application's microcontroller HV Header Value ISDN Integrated Services Digital Network ISM Industrial, Scientific and Medical ksamples/s Kilosamples per second L2CAP Logical Link Control and Adaptation Protocol (protocol layer) LC Link Controller JBSD Master in Serial Out OHCI Open Host Controller Interface PA Power Amplifier PCB Printed Circuit Board PCB Printed Controller <td></td> <td></td> <td></td>			
BER Bit Error Rate. Used to measure the quality of a link C/I Carrier Over Interferer CMOS Complementary Metal Oxide Semiconductor CODEC Coder Decoder CPU Central Processing Unit CQDDR Channel Quality Driven Data Rate CTS Clear to Send CVSD Continuous Variable Slope Delta Modulation DAC Digital to Analogue Converter dBm Decicles relative to 1mW DC Direct Current DFU Device Firmware Upgrade GCI General Circuit Interface. Standard synchronous 2B+D ISDN timing interface Host Application's microcontroller Host Controller Interface Host Host Application's microcontroller IsDN Integrated Arrives Digital Network ISDN Integrated Services Digital Network ISM Industrial, Scientific and Medical ksamples/s kilosamples per second L2CAP Logical Link Control and Adaptation Protocol (protocol layer) LC Link Controller LBS Least-Significant Bit<		BlueCore M Serial Protocol	
C/I Carrier Over Interferer CMOS Complementary Metal Oxide Semiconductor CODEC Coder Decoder CPU Central Processing Unit CQDDR Channel Quality Driven Data Rate CTS Clear to Send CVSD Controllows Variable Stope Detta Modulation DAC Digital to Analogue Converter dBm Decibels relative to 1mW DFU Device Firmware Upgrade GCI General Circuit Interface. HOI Host Controller Interface Host Application's microcontroller Host Application's microcontroller HV Header Value ISDN Integrated Services Digital Network ISDN Integrated Services Digital Network ISM Industrial, Scientific and Medical ksamples/s kilosamples per second L2CAP Logical Link Control and Adaptation Protocol (protocol layer) LC Link Controller LSB Least-Significant Bit Praw Encoding standard MISO Master In Serial Out OHCI Open Host Controller Interface			
CMOS Complementary Metal Oxide Semiconductor CODEC Coder Decoder CPU Central Processing Unit CQDDR Channel Quality Driven Data Rate CTS Clear to Send CVSD Continuous Variable Slope Delta Modulation DAC Digital to Analogue Converter dBm Decibels relative to 1mW DC Direct Current DFU Device Firmware Uggrade GCI General Circuit Interface. Standard synchronous 2B+D ISDN timing interface Host Application's microcontroller Host Controller Interface Host Host Controller Interface Kilosamples per second ISDN Integrated Services Digital Network ISM Industrific and Medical ksamples/s kilosamples per second LCAP Logical Link Controller Interface Plaw Encoding standard MISO Master In Serial Out OPC Open Host Controller Interface PA Power Amplifier PCB Printed Circuit Board PCM Power Ampli			
CODEC Coder Decoder CPU Central Processing Unit CQDDR Channel Quality Driven Data Rate CTS Clear to Send CVSD Continuous Variable Slope Delta Modulation DAC Digital to Analogue Converter dBm Decibels relative to 1mW DC Direct Current DFU Device Firmware Uggrade GCI General Circuit Interface. Standard synchronous 2B+D ISDN timing interface Hot Host Controller Interface. Standard synchronous 2B+D ISDN timing interface Hot Application's microcontroller Host Controller Bluetooth integrated chip HV Header Value ISDN Integrated Services Digital Network ISM Industrial, Scientific and Medical ksamples/s kilosamples per second L2CAP Logical Link Control and Adaptation Protocol (protocol layer) LC Link Controller LSB Least.Significant Bit p-law Encoding standard MISO Master In Serial Out OHCI Open Host Controller Interface PA Power Amplifier			
CPU Central Processing Unit CQDDR Channel Quality Driven Data Rate CTS Clear to Send CVSD Continuous Variable Slope Delta Modulation DAC Digital to Analogue Converter dBm Decibels relative to 1mW DC Direct Current DFU Device Firmware Upgrade GCI General Circuit Interface. Standard synchronous 2B+D ISDN timing interface HOI Host Controller Interface Host Application's microcontroller Host Controller Interface Host Controller Interface HSDN Integrated Services Digital Network ISM Integrated Services Digital Network ISM Integrated Services Digital Network ISM Industral, Scientific and Medical ksamples/s kilosamples per second L2CAP Logical Link Controller Interface PA Power Amplifier p-law Encoding standard MISO Master In Serial Out OHCI Open Host Controller Interface PA Power Amplifier PCB Printed Circuit Board PCM <td< td=""><td></td><td></td><td></td></td<>			
CODDR Channel Quality Driven Data Rate CTS Cilear to Send CVSD Continuous Variable Slope Delta Modulation DAC Digital to Analogue Converter dBm Decicels relative to 1mW DC Direct Current DFU Device Firmware Upgrade GC1 General Circuit Interface. HOI Host Controller Interface HOI Host Controller Interface Host Controller Bluetooth integrated chip HV Header Value ISDN Integrated Services Digital Network ISM Industrial, Scientific and Medical ksamples/s kilosamples per second LZCAP Logical Link Control and Adaptation Protocol (protocol layer) LC Link Controller JBSD Master In Serial Out OHCI Open Host Controller Interface PA Power Amplifier PCB Printed Circuit Board PCM Power Amplifier PCM Pulse Code Modulation. Refers to digital voice data PO Paralel Input Output RAM Radiom Access Memory			
CTS Clear to Send CVSD Continuous Variable Slope Delta Modulation DAC Digital to Analogue Converter dBm Decibels relative to 1mW DC Direct Current DFU Device Firmware Upgrade GCI General Circuit Interface. Standard synchronous 2B+D ISDN timing interface HOI Host Controller Interface Host Application's microcontroller Host Controller Integrated Services Digital Network Ist ISDN Integrated Services Digital Network ISM Industral, Scientific and Medical ksamples/s kilosamples per second L2CAP Logical Link Control and Adaptation Protocol (protocol layer) LC Link Controller Interface Paw Encoding standard MISO Master In Serial Out OHCI Open Host Controller Interface PA Power Amplifier PCB Printed Circuit Board PCB Printed Circuit Board PCB Printed Circuit Board PCB Printed Circuit Board PCB Protocol layer providing serial port emulation over L2CAP			
CVSD Continuous Variable Slope Delta Modulation DAC Digital to Analogue Converter dBm Decibels relative to 1mW DC Direct Current DFU Device Firmware Upgrade GCI General Circuit Interface. Standard synchronous 2B+D ISDN timing interface HGI Host Controller Interface Host Application's microcontroller Host Controller Bluetooth integrated chip HV Header Value ISDN Integrated Services Digital Network ISM Industrial, Scientific and Medical ksamples/s kilosamples per second L2CAP Logical Link Control and Adaptation Protocol (protocol layer) LC Link Controller LSB Least-Significant Bit p-law Encoding standard MISO Master In Serial Out OHCI Open Host Controller Interface PA Power Amplifier PCB Printed Circuit Board PCM Paialel Input Output RAM Radom Access Memory RF Radio Frequency RFCOMM Protocol layer providing serial			
DAC Digital to Analogue Converter dBm Decibels relative to ImW DC Direct Current DFU Device Firmware Upgrade GCI General Circuit Interface. Standard synchronous 2B+D ISDN timing interface HOI Host Controller Interface. Host Application's microcontroller Host Controller Bluetooth integrated chip HV Header Value ISDN Integrated Services Digital Network ISM Industrial, Scientific and Medical ksamples/s kilosamples per second L2CAP Logical Link Control and Adaptation Protocol (protocol layer) LC Link Controller LSB Least-Significant Bit p-law Encoding standard MISO Master In Serial Out OHCI Open Host Controller Interface PA Power Amplifier PCB Printed Circuit Board PCB Printed Circuit Board PIO Parallel Input Output RAM Radom Access Memory RF Radob Frequency <tr< td=""><td></td><td></td><td></td></tr<>			
dBm Decibels relative to 1mW DC Direct Current DFU Device Firmware Upgrade GCI General Circuit Interface. Standard synchronous 2B+D ISDN timing interface HCI Host Controller Interface Host Application's microcontroller Host Controller Bluetooth integrated chip HV Header Value ISDN Integrated Services Digital Network ISM Industrial, Scientific and Medical ksamples/s kilosamples per second L2CAP Logical Link Control and Adaptation Protocol (protocol layer) LC Link Controller Interface PA Poer Host Controller Interface PA Power Amplifier PCB Printed Circuit Board PCB Printed Circuit Board PCM Pulse Code Modulation. Refers to digital voice data PIO Parallel Input Output RAM Radio Frequency RFF Radio Frequency RFS Receive or Receiver RSI Receive or Receiver RSSI Receive or Receiver RSSI Receive or Signal Strength Indi			
DC Direct Current DFU Device Firmware Upgrade GCI General Circuit Interface. Standard synchronous 2B+D ISDN timing interface HCI Host Controller Interface Host Application's microcontroller Host Controller Bluetooth integrated chip HV Header Value ISDN Integrated Services Digital Network ISM Industrial, Scientific and Medical ksamples/s kilosamples per second L2CAP Logical Link Control and Adaptation Protocol (protocol layer) LC Link Controller LSB Least-Significant Bit p-law Encoding standard MISO Master In Serial Out OHCI Open Host Controller Interface PA Power Amplifier PCB Printed Circuit Board PIO Parallel Input Output RAM Radio Frequency RFCOMM Pulse Code Modulation. Refers to digital voice data PIO Parallel Input Output RAM Radiom Access Memory RF Radio Frequency	_		
DFU Device Firmware Upgrade GCI General Circuit Interface. Standard synchronous 2B+D ISDN timing interface HGI Host Controller Interface Host Application's microcontroller Host Controller Bluetooth integrated chip HV Header Value ISDN Integrated Services Digital Network ISM Industrial, Scientific and Medical ksamples/s kilosamples per second L2CAP Logical Link Control and Adaptation Protocol (protocol layer) LC Link Controller LSB Least-Significant Bit p-law Encoding standard MISO Master In Serial Out OHCI Open Host Controller Interface PA Power Amplifier PCB Printed Circuit Board PCM Pulse Code Modulation. Refers to digital voice data PIO Parallel Input Output RAM Random Access Memory RF Radio Frequency RF Radio Frequency RF Radio Frequency RF Reduced Instruction Set Computer			
GCI General Circuit Interface Standard synchronous 2B+D ISDN timing interface HCI Host Controller Interface Host Controller Interface Host Controller Bluetooth integrated chip Host Controller HV Header Value Integrated Services Digital Network ISDN Integrated Services Digital Network ISM Industrial, Scientific and Medical ksamples/s kilosamples per second L2CAP Logical Link Control and Adaptation Protocol (protocol layer) LC Link Controller LSB Least-Significant Bit p-law Encoding standard MISO Master In Serial Out OHCI Open Host Controller Interface PA Power Amplifier PCB Printed Circuit Board PIO Parallel Input Output RAM Radom Access Memory RF Radio Frequency RFCOMM Protocol layer providing serial port emulation over L2CAP RISC Reduced Instruction Set Computer RSSI Receive of Receiver RCO Synchronous Connection-Oriented. Voice oriented Bluetooth packet SDP	= •		
HCI Host Controller Host Application's microcontroller Host Controller Bluetooth integrated chip HV Header Value ISDN Integrated Services Digital Network ISM Industrial, Scientific and Medical ksamples/s kilosamples per second L2CAP Logical Link Control and Adaptation Protocol (protocol layer) LC Link Controller LSB Least-Significant Bit p-law Encoding standard MISO Master in Serial Out OHCI Open Host Controller Interface PA Power Amplifier PCB Printed Circuit Board PCM Pulse Code Modulation. Refers to digital voice data PIO Parallel Input Output RAM Randon Access Memory RF Radio Frequency RFCOMM Protocol layer providing serial port emulation over L2CAP RISC Reduced Instruction Set Computer RSSI Receive Signal Strength Indication RTS Ready To Send RX Receive or Receiver SCO Synchronous Connection-Oriented. Voice		Center I Initiate Opgrade	
Host Application's microcontroller Host Controller Bluetooth integrated chip HV Header Value ISDN Integrated Services Digital Network ISM Industrial, Scientific and Medical ksamples/s kilosamples per second L2CAP Logical Link Control and Adaptation Protocol (protocol layer) LC Link Controller LSB Least-Significant Bit p-law Encoding standard MISO Master In Serial Out OHCI Open Host Controller Interface PA Power Amplifier PCB Printed Circuit Board PIO Parallel Input Output RAM Random Access Memory RF Radio Frequency RFCOMM Protocol layer providing serial port emulation over L2CAP RISC Reduced Instruction Set Computer RSSI Receive or Receiver SCO Synchronous Connection-Oriented. Voice oriented Bluetooth packet SDP Service Discovery Protocol SIG Special Interest Group SPI Serial Peripheral Interface SPP Serial Perip			
Host Controller Bluetooth integrated chip HV Header Value ISDN Integrated Services Digital Network ISM Industrial, Scientific and Medical ksamples/s kilosamples per second L2CAP Logical Link Control and Adaptation Protocol (protocol layer) LC Link Controller LSB Least-Significant Bit p-law Encoding standard MISO Master In Serial Out OHCI Open Host Controller Interface PA Power Amplifier PCB Printed Circuit Board PIO Parallel Input Output RAM Radio Frequency RF Radio Frequency RFCOMM Protocol layer providing serial port emulation over L2CAP RISC Reduced Instruction Set Computer RSSI Receive Signal Strength Indication RTS Ready To Send RX Receive or Receiver SCO Synchronous Connection-Oriented. Voice oriented Bluetooth packet SDP Service Discovery Protocol SIG Special Interest Group SPI Serial Port Profile	-		
HV Header Value ISDN Integrated Services Digital Network ISM Industrial, Scientific and Medical ksamples/s kilosamples per second L2CAP Logical Link Control and Adaptation Protocol (protocol layer) LC Link Controller LSB Least-Significant Bit p-law Encoding standard MISO Master In Serial Out OHCI Open Host Controller Interface PA Power Amplifier PCB Printed Circuit Board PIO Parallel Input Output RAM Random Access Memory RF Radio Frequency RISC Reduced Instruction Set Computer RISC Reduced Instruction Set Computer RSI Receive Signal Strength Indication RTS Ready To Send RX Receive or Receiver SCO Synchronous Connection-Oriented. Voice oriented Bluetooth packet SDP Service Discovery Protocol SIG Special Interest Group SP Serial Port Profile SPP Serial Port Profile SPP <			
ISDN Integrated Services Digital Network ISM Industrial, Scientific and Medical ksamples/s kilosamples per second L2CAP Logical Link Control and Adaptation Protocol (protocol layer) LC Link Control and Adaptation Protocol (protocol layer) LC Link Control and Adaptation Protocol (protocol layer) LBB Least-Significant Bit p-law Encoding standard MISO Master In Serial Out OHCI Open Host Controller Interface PA Power Amplifier PCB Printed Circuit Board PCM Pulse Code Modulation. Refers to digital voice data PIO Parallel Input Output RAM Random Access Memory RF Radio Frequency RFCOMM Protocol layer providing serial port emulation over L2CAP RISC Reduced Instruction Set Computer RSSI Receive Signal Strength Indication RTS Ready To Send RX Receive or Receiver SCO Synchronous Connection-Oriented. Voice oriented Bluetooth packet SDP Serial Peripheral Interface SPP Seria			
ISMIndustrial, Scientific and Medicalksamples/skilosamples per secondL2CAPLogical Link Control and Adaptation Protocol (protocol layer)LCLink ControllerLSBLeast-Significant Bitp-lawEncoding standardMISOMaster In Serial OutOHCIOpen Host Controller InterfacePAPower AmplifierPCBPrinted Circuit BoardPIOParallel Input OutputRAMRandom Access MemoryRFRadio FrequencyRISCReduce Instruction Set ComputerRSSIReceive Signal Strength IndicationRTSReady To SendRXReceive Or ReceiverSCOSynchronous Connection-Oriented. Voice oriented Bluetooth packetSDPService Discovery ProtocolSIGSpecial Interest GroupSPISerial Port ProfileTBDTo Be Defined			
ksamples/skilosamples per secondL2CAPLogical Link Control and Adaptation Protocol (protocol layer)LCLink ControllerLSBLeast-Significant Bitp-lawEncoding standardMISOMaster In Serial OutOHCIOpen Host Controller InterfacePAPower AmplifierPCBPrinted Circuit BoardPIOParallel Input OutputRAMRandom Access MemoryRFRadio FrequencyRFSIReceive Signal Strength IndicationRTSReceive Signal Strength IndicationRTSReceive Signal InterfaceSCOSynchronous Connection-Oriented. Voice oriented Bluetooth packetSDPService Discovery ProtocolSIGSpecial Interest GroupSPISerial Peripheral InterfaceSPPSerial Port ProfileTBDTo Be Defined			
L2CAP Logical Link Control and Adaptation Protocol (protocol layer) LC Link Controller LSB Least-Significant Bit p-law Encoding standard MISO Master In Serial Out OHCI Open Host Controller Interface PA Power Amplifier PCB Printed Circuit Board PIO Patallel Input Output RAM Random Access Memory RF Radio Frequency RFCOMM Protocol layer providing serial port emulation over L2CAP RISC Reduced Instruction Set Computer RSSI Receive Signal Strength Indication RTS Ready To Send RX Receive or Receiver SCO Synchronous Connection-Oriented. Voice oriented Bluetooth packet SDP Service Discovery Protocol SIG Special Interest Group SPI Serial Peripheral Interface SPP Serial Port Profile TBD To Be Defined			
LCLink ControllerLSBLeast-Significant Bitp-lawEncoding standardMISOMaster In Serial OutOHCIOpen Host Controller InterfacePAPower AmplifierPCBPrinted Circuit BoardPCMPulse Code Modulation. Refers to digital voice dataPIOParallel Input OutputRAMRandom Access MemoryRFRadio FrequencyRFCOMMProtocol layer providing serial port emulation over L2CAPRISCReduced Instruction Set ComputerRSSIReceive Signal Strength IndicationRTSReady To SendRXReceive or ReceiverSCOSynchronous Connection-Oriented. Voice oriented Bluetooth packetSDPService Discovery ProtocolSIGSpecial Interest GroupSPISerial Port ProfileTBDTo Be Defined			
LSB Least-Significant Bit p-law Encoding standard MISO Master In Serial Out OHCI Open Host Controller Interface PA Power Amplifier PCB Printed Circuit Board PCM Pulse Code Modulation. Refers to digital voice data PIO Parallel Input Output RAM Random Access Memory RF Radio Frequency RFCOMM Protocol layer providing serial port emulation over L2CAP RISC Reduced Instruction Set Computer RSSI Receive Signal Strength Indication RTS Ready To Send RX Receive or Receiver SCO Synchronous Connection-Oriented. Voice oriented Bluetooth packet SDP Service Discovery Protocol SIG Special Interest Group SPI Serial Peripheral Interface SPP Serial Port Profile TBD To Be Defined			
p-lawEncoding standardMISOMaster In Serial OutOHCIOpen Host Controller InterfacePAPower AmplifierPCBPrinted Circuit BoardPCMPulse Code Modulation. Refers to digital voice dataPIOParallel Input OutputRAMRandom Access MemoryRFRadio FrequencyRFCOMMProtocol layer providing serial port emulation over L2CAPRISCReduced Instruction Set ComputerRSSIReceive Signal Strength IndicationRXReceive or ReceiverSCOSynchronous Connection-Oriented. Voice oriented Bluetooth packetSDPService Discovery ProtocolSIGSpecial Interest GroupSPISerial Peripheral InterfaceSPPSerial Port ProfileTBDTo Be Defined	-		
MISO Master In Serial Out OHCI Open Host Controller Interface PA Power Amplifier PCB Printed Circuit Board PCM Pulse Code Modulation. Refers to digital voice data PIO Parallel Input Output RAM Random Access Memory RF Radio Frequency RFCOMM Protocol layer providing serial port emulation over L2CAP RISC Reduced Instruction Set Computer RSSI Receive Signal Strength Indication RX Receive or Receiver SCO Synchronous Connection-Oriented. Voice oriented Bluetooth packet SDP Service Discovery Protocol SIG Special Interest Group SPI Serial Peripheral Interface SPP Serial Port Profile TBD To Be Defined			
OHCIOpen Host Controller InterfacePAPower AmplifierPCBPrinted Circuit BoardPCMPulse Code Modulation. Refers to digital voice dataPIOParallel Input OutputRAMRandom Access MemoryRFRadio FrequencyRFCOMMProtocol layer providing serial port emulation over L2CAPRISCReduced Instruction Set ComputerRSSIReceive Signal Strength IndicationRXReceive or ReceiverSCOSynchronous Connection-Oriented. Voice oriented Bluetooth packetSDPService Discovery ProtocolSIGSpecial Interest GroupSPISerial Peripheral InterfaceSPPSerial Port ProfileTBDTo Be Defined			
PA Power Amplifier PCB Printed Circuit Board PCM Pulse Code Modulation. Refers to digital voice data PIO Parallel Input Output RAM Random Access Memory RF Radio Frequency RFCOMM Protocol layer providing serial port emulation over L2CAP RISC Reduced Instruction Set Computer RSSI Receive Signal Strength Indication RTS Ready To Send RX Receive or Receiver SCO Synchronous Connection-Oriented. Voice oriented Bluetooth packet SDP Service Discovery Protocol SIG Special Interest Group SPI Serial Peripheral Interface SPP Serial Port Profile TBD To Be Defined			
PCB Printed Circuit Board PCM Pulse Code Modulation. Refers to digital voice data PIO Parallel Input Output RAM Random Access Memory RF Radio Frequency RFCOMM Protocol layer providing serial port emulation over L2CAP RISC Reduced Instruction Set Computer RSSI Receive Signal Strength Indication RTS Ready To Send RX Receive or Receiver SCO Synchronous Connection-Oriented. Voice oriented Bluetooth packet SDP Service Discovery Protocol SIG Special Interest Group SPI Serial Peripheral Interface SPP Serial Port Profile TBD To Be Defined			
PCM Pulse Code Modulation. Refers to digital voice data PIO Parallel Input Output RAM Random Access Memory RF Radio Frequency RFCOMM Protocol layer providing serial port emulation over L2CAP RISC Reduced Instruction Set Computer RSSI Receive Signal Strength Indication RTS Ready To Send RX Receive or Receiver SCO Synchronous Connection-Oriented. Voice oriented Bluetooth packet SDP Service Discovery Protocol SIG Special Interest Group SPI Serial Peripheral Interface SPP Serial Port Profile TBD To Be Defined			
PIO Parallel Input Output RAM Random Access Memory RF Radio Frequency RFCOMM Protocol layer providing serial port emulation over L2CAP RISC Reduced Instruction Set Computer RSSI Receive Signal Strength Indication RTS Ready To Send RX Receive or Receiver SCO Synchronous Connection-Oriented. Voice oriented Bluetooth packet SDP Service Discovery Protocol SIG Special Interest Group SPI Serial Peripheral Interface SPP Serial Port Profile TBD To Be Defined			
RAM Random Access Memory RF Radio Frequency RFCOMM Protocol layer providing serial port emulation over L2CAP RISC Reduced Instruction Set Computer RSSI Receive Signal Strength Indication RTS Ready To Send RX Receive or Receiver SCO Synchronous Connection-Oriented. Voice oriented Bluetooth packet SDP Service Discovery Protocol SIG Special Interest Group SPI Serial Peripheral Interface SPP Serial Port Profile TBD To Be Defined		0	
RFRadio FrequencyRFCOMMProtocol layer providing serial port emulation over L2CAPRISCReduced Instruction Set ComputerRSSIReceive Signal Strength IndicationRTSReady To SendRXReceive or ReceiverSCOSynchronous Connection-Oriented. Voice oriented Bluetooth packetSDPService Discovery ProtocolSIGSpecial Interest GroupSPISerial Peripheral InterfaceSPPSerial Port ProfileTBDTo Be Defined			
RFCOMM Protocol layer providing serial port emulation over L2CAP RISC Reduced Instruction Set Computer RSSI Receive Signal Strength Indication RTS Ready To Send RX Receive or Receiver SCO Synchronous Connection-Oriented. Voice oriented Bluetooth packet SDP Service Discovery Protocol SIG Special Interest Group SPI Serial Peripheral Interface SPP Serial Port Profile TBD To Be Defined			
RISC Reduced Instruction Set Computer RSSI Receive Signal Strength Indication RTS Ready To Send RX Receive or Receiver SCO Synchronous Connection-Oriented. Voice oriented Bluetooth packet SDP Service Discovery Protocol SIG Special Interest Group SPI Serial Peripheral Interface SPP Serial Port Profile TBD To Be Defined			
RSSI Receive Signal Strength Indication RTS Ready To Send RX Receive or Receiver SCO Synchronous Connection-Oriented. Voice oriented Bluetooth packet SDP Service Discovery Protocol SIG Special Interest Group SPI Serial Peripheral Interface SPP Serial Port Profile TBD To Be Defined		Protocol layer providing serial port emulation over L2CAP	
RTS Ready To Send RX Receive or Receiver SCO Synchronous Connection-Oriented. Voice oriented Bluetooth packet SDP Service Discovery Protocol SIG Special Interest Group SPI Serial Peripheral Interface SPP Serial Port Profile TBD To Be Defined			
RX Receive or Receiver SCO Synchronous Connection-Oriented. Voice oriented Bluetooth packet SDP Service Discovery Protocol SIG Special Interest Group SPI Serial Peripheral Interface SPP Serial Port Profile TBD To Be Defined			
SCO Synchronous Connection-Oriented. Voice oriented Bluetooth packet SDP Service Discovery Protocol SIG Special Interest Group SPI Serial Peripheral Interface SPP Serial Port Profile TBD To Be Defined	-		
SDP Service Discovery Protocol SIG Special Interest Group SPI Serial Peripheral Interface SPP Serial Port Profile TBD To Be Defined			
SIG Special Interest Group SPI Serial Peripheral Interface SPP Serial Port Profile TBD To Be Defined			
SPI Serial Peripheral Interface SPP Serial Port Profile TBD To Be Defined	-		
SPP Serial Port Profile TBD To Be Defined			
TBD To Be Defined			
	-		
TX Transmit or Transmitter			
UART Universal Asynchronous Receiver Transmitter	_		
USB Universal Serial Bus or Upper Side Band (depending on context)			
VM Virtual Machine	VM		
www world wide web	www	world wide web	



Contact information

For support questions please contact your local dealer For other purposes use: info@free2move.net Website: www.free2move.net

Local dealer/distributor

The information given herein includes text, drawings, illustrations and schematics that are believed to be reliable. However, Free2move makes no warranties as to its accuracy or completeness and disclaims any liability in connection with its use. Free2move will in no case be liable for any incidental, indirect or consequential damages arising out of sale, resale, use or misuse of the product. Users of Free2move products should make their own evaluation to determine the suitability of each such product for the specific application.